Docket No.: M4065.0528/P528-A

(PATENT)

### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Cem Basceri, et al.

Application No.: Not Yet Assigned

Group Art Unit: 2814

Filed: September 11, 2003

Examiner: N. Ha

For: MIS CAPACITOR AND METHOD OF

**FORMATION** 

# FIRST PRELIMINARY AMENDMENT

### Box Non-Fee Amendment

Commissioner for Patents Washington, DC 20231

Dear Sir:

Prior to examination on the merits, please amend the above-identified U.S. patent application as follows:

# In the Specification

Page 2, after the title, please insert --This application is a divisional of Application Ser. No. 10/145,993, filed May 16, 2002, the disclosure of which is incorporated by reference herein.--

# In the Claims

Please cancel claims 1-64.

Please amend claims 69 and 77-79 as shown.

Application No.: Not Yet Assigned Docket No.: M4065.0528/P528

69. (Amended) The method of claim 69 68, wherein said act of etching said layer of hemispherical grained polysilicon further comprises contacting said layer of hemispherical grained polysilicon with a solution of HF.

- 77. (Amended) The method of claim 77. (Amended) The method of claim 77. (Amended) The method of claim 77. (Amended) and act of providing said boron-doped titanium nitride layer further comprises the act of incorporating boron into a titanium nitride layer.
- 78. (Amended) The method of claim 78  $\overline{78}$ , wherein said act of incorporating boron into a titanium nitride layer further comprises the act of exposing said titanium nitride layer to  $B_2H_6$ .
- 79. (Amended) The method of claim 79.78, wherein said act of incorporating boron into a titanium nitride layer further comprises the act of exposing said titanium nitride layer to  $B_2H_6$  at a temperature of about 200°C to about 600°C.